

THERMALLY ENHANCED LID FOR MULTICHIP MODULES

ABSTRACT

An electronic package having one or more components comprising: a substrate having a first coefficient of thermal expansion; a lid attached to the substrate, the lid including a vapor chamber, the lid having a second coefficient of thermal expansion, the first coefficient of thermal expansion matched to the second coefficient of expansion; a thermal transfer medium in contact with a back surface of each component and an outer surface of a lower wall of the lid; and each component electrically connected to a top surface of the substrate.